

Amendments to the Specification

Please replace the paragraph number [1] with the following revised paragraph:

[1] This application is a continuation in part of and claims priority from co-pending U.S. Patent Application No. 10/404,270, filed on March 31, 2003, entitled "Vertical Proximity Processor," which is a continuation-in-part and claims priority from co-pending U.S. Patent Application No. 10/330,843 filed on December 24, 2002 and entitled "Meniscus, Vacuum, IPA Vapor, Drying Manifold," which is a continuation-in-part of co-pending U.S. Patent Application No. 10/261,839 filed on September 30, 2002 and entitled "Method and Apparatus for Drying Semiconductor Wafer Surfaces Using a Plurality of Inlets and Outlets Held in Close Proximity to the Wafer Surfaces." This application is also a continuation in part of U.S. Patent Application No. 10/330,897, filed on December 24, 2002, entitled "System for Substrate Processing with Meniscus, Vacuum, IPA vapor, Drying Manifold" ~~and is also a continuation in part of U.S. Patent Application No. 10/404,270, filed on March 31, 2003, entitled "Vertical Proximity Processor,"~~ and is also a continuation in part of U.S. Patent Application No. 10/404,692 filed on March 31, 2003, entitled Methods and Systems for Processing a Substrate Using a Dynamic Liquid Meniscus. The aforementioned patent applications are hereby incorporated by reference in their entirety.